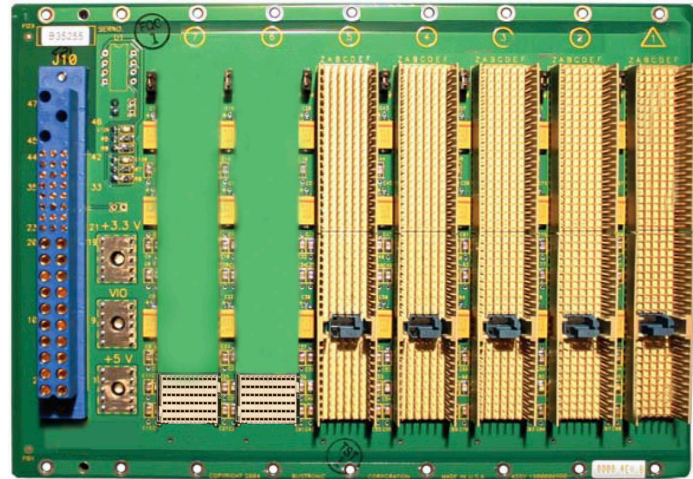


BP3105

3U CompactPCI[®] PlusIO backplane

- Conforms to latest PICMG
- 10-layer, high-performance, low noise stripline design
- Custom configurations available
- PICMG 2.0 R3.0 CompactPCI specification compliant
- PICMG 2.1 R1.0 cPCI Hot Swap specification compliant
- Hybrid configuration provides 6 x standard CPCI slots and 2 x CPCI Serial (S.0) peripheral slots
- V(I/O) adjustable to +3.3 V or +5 V
- Digital GND can be connected to isolated from chassis GND by means of screws
- P47 power connector



**Embedded
Solutions**

SKYTOP ELECTRONICS Ltd

Technical Data

Electrical Specifications

- Backplane Connectors: IEC 1076-4-101, 2 mm press-fit pin and socket
- Connector Pitch: 4 HP (0.8") spacing
- Insulation Resistance: acc. IEC 512-5
- Transmission Rate:
 - 132 Mbytes/s (peak) for 32-bit transmissions @ 33 MHz
 - 264 Mbytes/s (peak) for 32-bit transmissions @ 66 MHz
- Characteristic of Impedance: 65 ohms $\pm 10\%$

Mechanical Specifications

- Dimensions: conforming to CompactPCI[®] specification for 3U boards
- Weight: 200g
- Backplane Material: FR4

Environmental Specifications

- Temperature range (operation): -40..+85°C
- Temperature range (storage): -40..+85°C
- Relative humidity (operation): max. 95% non-condensing
- Relative humidity (storage): max. 95% non-condensing
- Altitude: -300m to + 3,000m
- Shock: 15g/11ms
- Bump: 10g/16ms
- Vibration (sinusoidal): 2g/10..200Hz
- Conformal coating on request

MTBF

500 000 h @ 40°C (derived from MIL-HDBK-217F)

Contact Information

Hong Kong

SKYTOP ELECTRONICS Ltd
Rm 619, Park Fook Ind., Bldg.,
615-617 Tai NaN West Street, Kowloon

Tel: + 852 35979249
+ 852 52876473

www.skytop-electronics.com
info@skytop-electronics.com

SKYTOP ELECTRONICS Ltd keeps the right to change technical specification without further notice.
All trademarks mentioned are property of their respective owners.